L Number	Hits	Search Text	DB	Time stamp
3	1221	(silicon with (mold or mould)).ti.	USPAT;	2003/10/09 17:59
			US-PGPUB;	
		· ·	EPO; JPO;	
			DERWENT	
6	2510	((mold or mould) and (cap or lid) and semiconductor)	USPAT;	2003/10/09 17:59
			US-PGPUB;	
			EPO; JPO;	
			DERWENT	
1	4	("4436439" "4372694" "6158907" "5559932").PN.	USPAT;	2003/10/09 17:59
		· ·	US-PGPUB	
2	55	(silicon with (mold or mould)) and (semiconductor same cap)	USPAT;	2003/10/09 17:59
			US-PGPUB;	
			EPO; JPO;	
			DERWENT	
4	174	(mold or mould or die) and (semiconductor same caps same	USPAT;	2003/10/09 17:59
		wafer)	US-PGPUB;	
-			EPO; JPO;	
			DERWENT	
5	1	(wafer with silicon with (mold or mould) with microstructure)	USPAT;	2003/10/09 17:59
			US-PGPUB	
7	25	((mold or mould) and (cap or lid) and semiconductor).ti.	USPAT;	2003/10/09 17:59
1			US-PGPUB;	
			EPO; JPO;	
			DERWENT	*
8	1	("20020122972").PN.	USPAT;	2003/10/09 18:15
			US-PGPUB	· / / · /
9	4	(("4436439") or ("4372694") or ("6158907") or	USPAT;	2003/10/09 18:42
		("5559932")).PN.	US-PGPUB	
10	1645	((249/134) or (249/160) or (249/162)).CCLS.	USPAT;	2003/10/09 18:56
			US-PGPUB	
11	593	((425/408) or (425/416)).CCLS.	USPAT;	2003/10/09 19:01
			US-PGPUB	
12	430	(425/383).CCLS.	USPAT;	2003/10/09 19:02
			US-PGPUB	